

Webinar series: 5G Device Testing Journey

VALIDATION OF DIGITAL DESIGN OF NEXT GEN DEVICES

CS Wong
Oscilloscope Product Manager Asia

ROHDE & SCHWARZ

Make ideas real





4th May

Validation of digital design of next gen devices



11th May

Challenges to 5G mmWave component characterization



25th May

Simplifying 5G mobile device testing



1st June

ONE tool for automated device testing



8th June

Making 5G lab testing more realistic with R&S®CM360°



15th June

Production test strategies and smart solutions

5G DEVICE TESTING JOURNEY

Webinar Series

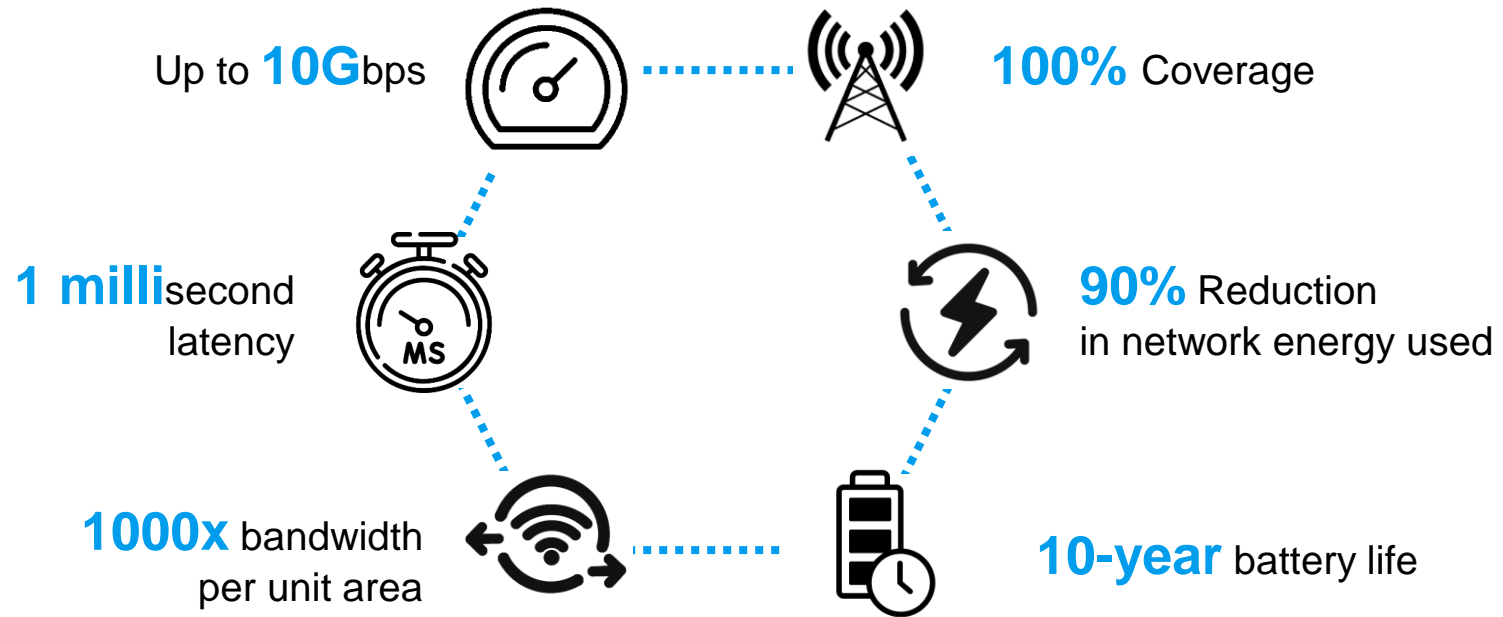
TOPICS

- ▶ What is in next gen?
- ▶ Base Station / Cellular Device Architecture
- ▶ High Speed Digital Interfaces
- ▶ Power Integrity
- ▶ Summary

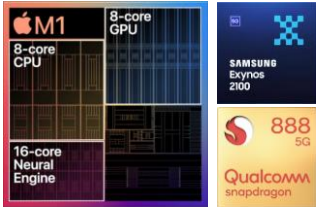


Validation of digital design of next gen devices

KEY DRIVERS BEHIND THE NEXT GEN NETWORK & DEVICES



DIGITAL LEAP IN NEXT GEN DEVICES



Warp-Speed processing



Camera Resolution



Crystal Clear Display Refresh Rate



Connectivity



Battery Life

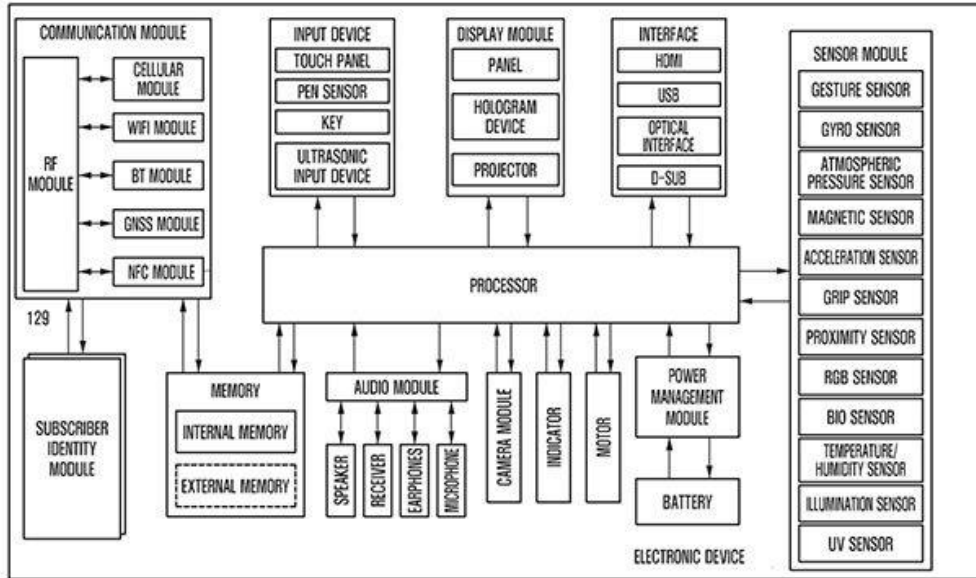


DEVICES ARE COMPLEX SYSTEM

SAMSUNG

BLOCK DIAGRAM

LETSGO DIGITAL



NEXT GEN DEVICES TRENDS

Digital Design & Power Trends

- ▶ Memory: LPDDR4 -> LPDDR4x -> LPDDR5 starts
- ▶ Digital Processor: 7nm -> 5nm -> 3nm planned for 21/22
- ▶ Display interface: higher resolution
- ▶ Camera interface: higher resolution
- ▶ Additional sensors / health features
- ▶ Data / charging: USB -> USB Type C -> Wireless / Wireless Charging (Qi)
- ▶ Power management: plenty of PMICs
- ▶ Battery technologies: longer battery time
- ▶ Integration: Multi-chip, System-on-a-chip, etc.

RF Trends

- ▶ More Radios for new cellular and non-cellular standards
- ▶ MIMO antennas

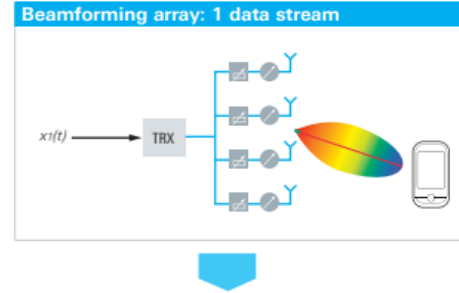
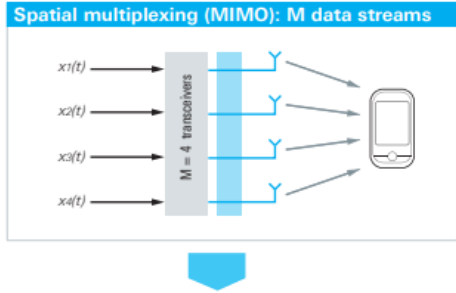


INCREASING MIMO DEGREES & BEAMFORMING

Increase data rates and energy efficiency:

- ▶ increase bandwidth (mmWave)
- ▶ massive MIMO
- ▶ beamforming
- ▶ virtualized network architecture

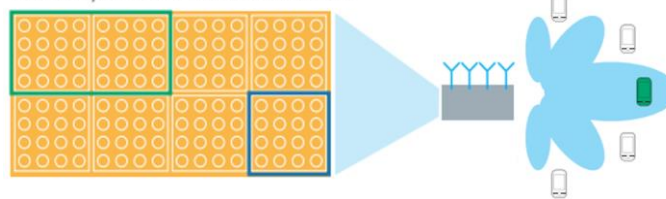
MIMO:
Multiple antennas at the TxRx to increase capacity.



Beamforming:
Increases antenna gain by bundling transmitted energy and directing it towards the user.

Massive MIMO: Very high number of antenna elements at the transceiver.
Combination of beamforming and spatial multiplexing.

Massive arrays of 128 to 1024 active antenna elements



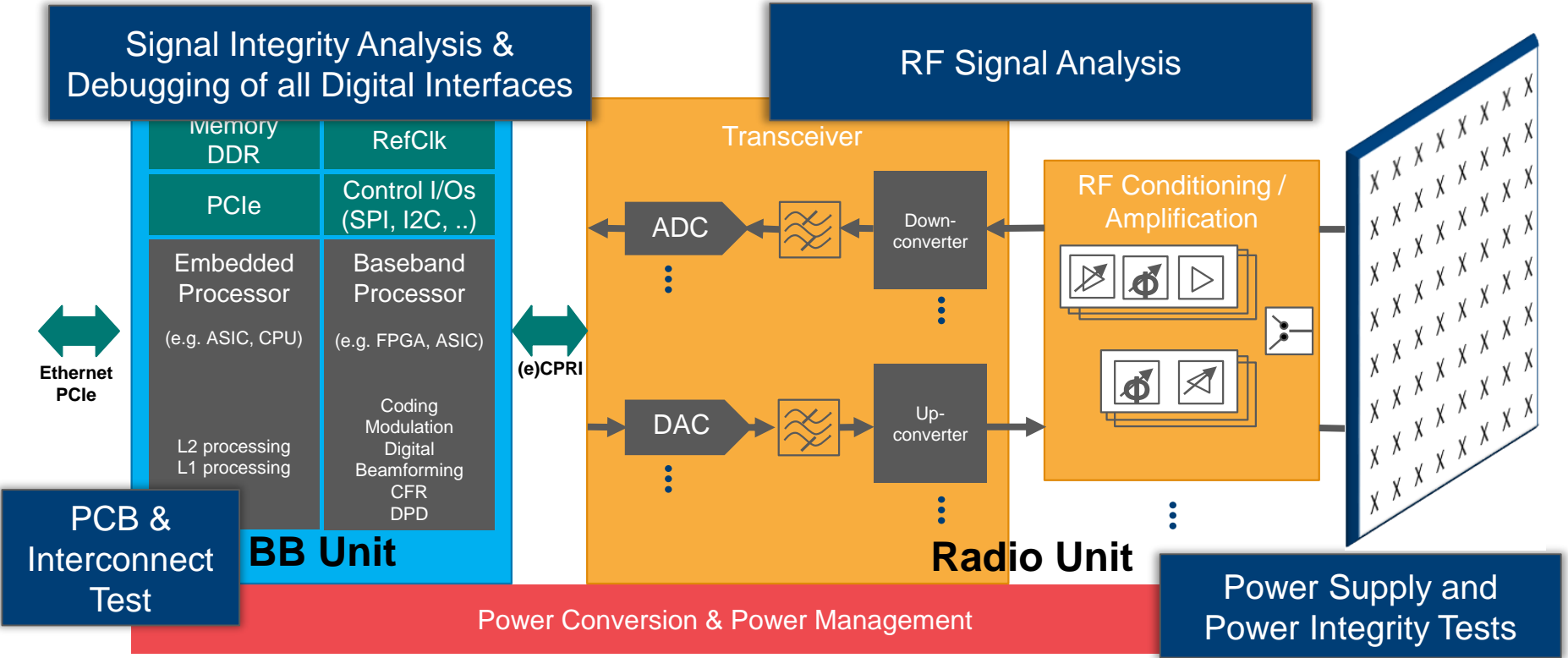
Increasing demand for higher MIMO degree.
Operators with mid-band spectrum show greater confidence in Massive MIMO, e.g. China, US.
Beamforming as an essential measure to increase system efficiency, especially for mmWave.

BASE STATION / CELLULAR DEVICE ARCHITECTURE

Review of key components and how to address their testing.

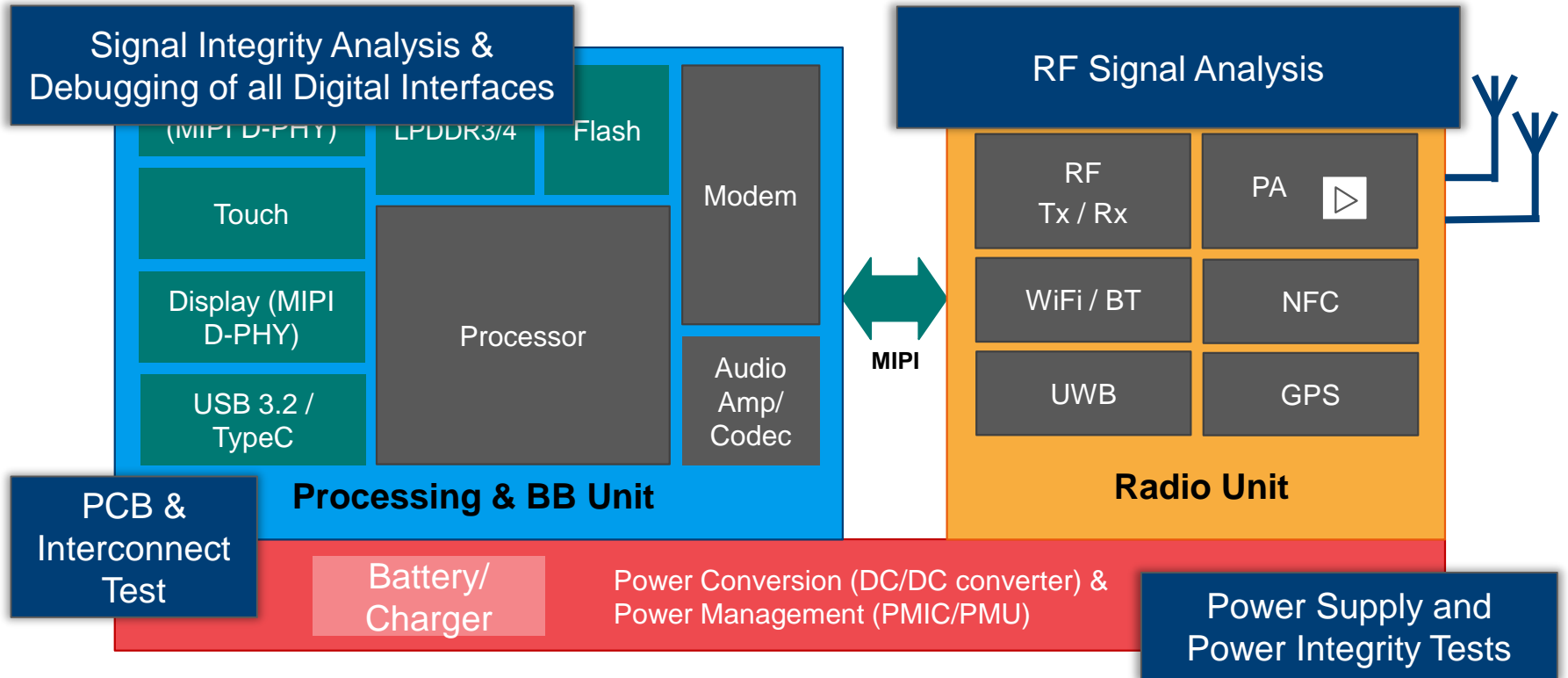
5G BASE STATION ARCHITECTURE

Digital Design, Power and RF Components

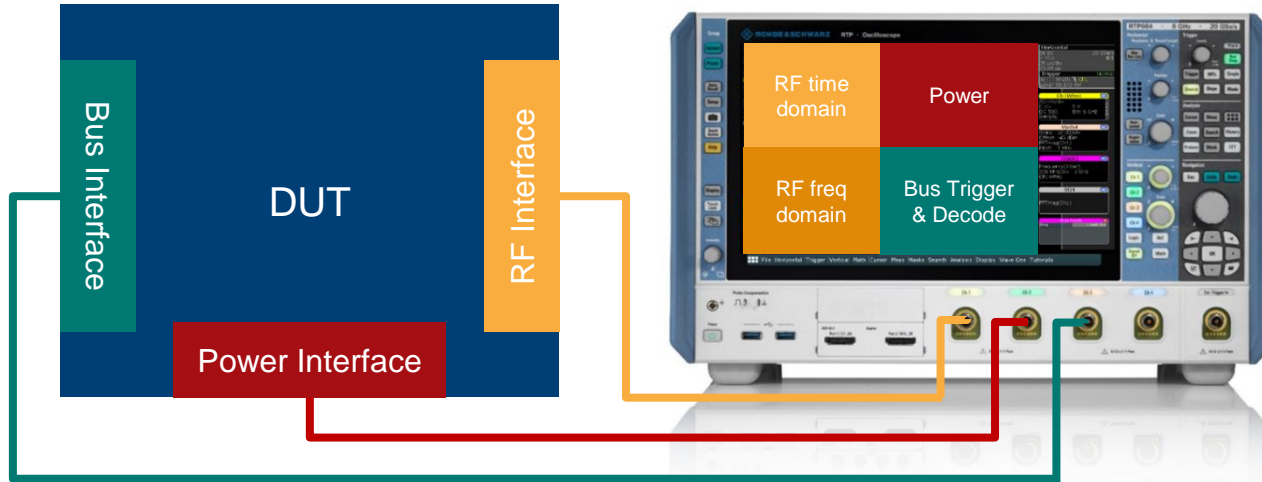


5G CELLULAR DEVICES ARCHITECTURE

Digital Design, Power and RF Components



SYSTEM-LEVEL DEBUGGING MULTIDOMAIN ANALYSIS



CAN,UART ... MIPI-RFFE
CIPR, Ethernet, PCIe,
USB, MIPI-DPHY, (LP)DDR, etc.

System-level Debugging

- ▶ Combine multiple measurements from different DUT interfaces on the same screen
- ▶ Look for possible correlations to determine causes of signal anomalies

HIGH SPEED DIGITAL INTERFACES

Why fast and reliable signal integrity solutions including PCB and interconnect tests are so important for integration of High Speed Digital Interfaces?

HIGHSPEED DIGITAL INTERFACES CHALLENGES

- ▶ Signal integrity challenges due to increasing data rates
- ▶ Interference issues due to increasing level of integration

For optimal Signal Integrity analysis – T&M equipment needs to collect statistical data fast.

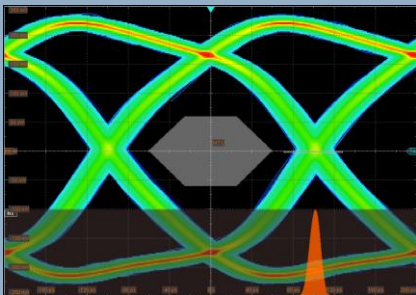


HIGH SPEED DIGITAL INTERFACES

Require Dedicated Tests for Verification & Debugging

Eye Diagram

- ▶ Fast update rate for statistical confidence
- ▶ Continuously operating Clock-Data-Recovery (CDR)
- ▶ Mask tests
- ▶ Deembedding function to compensate transmission loss



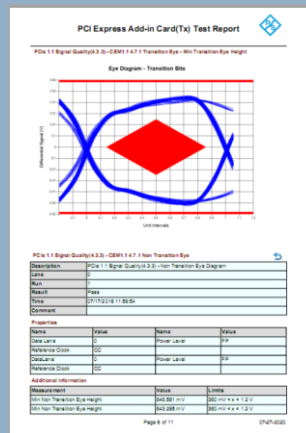
Jitter Analysis

- ▶ Break-down of jitter and noise into individual components for characterization & debugging



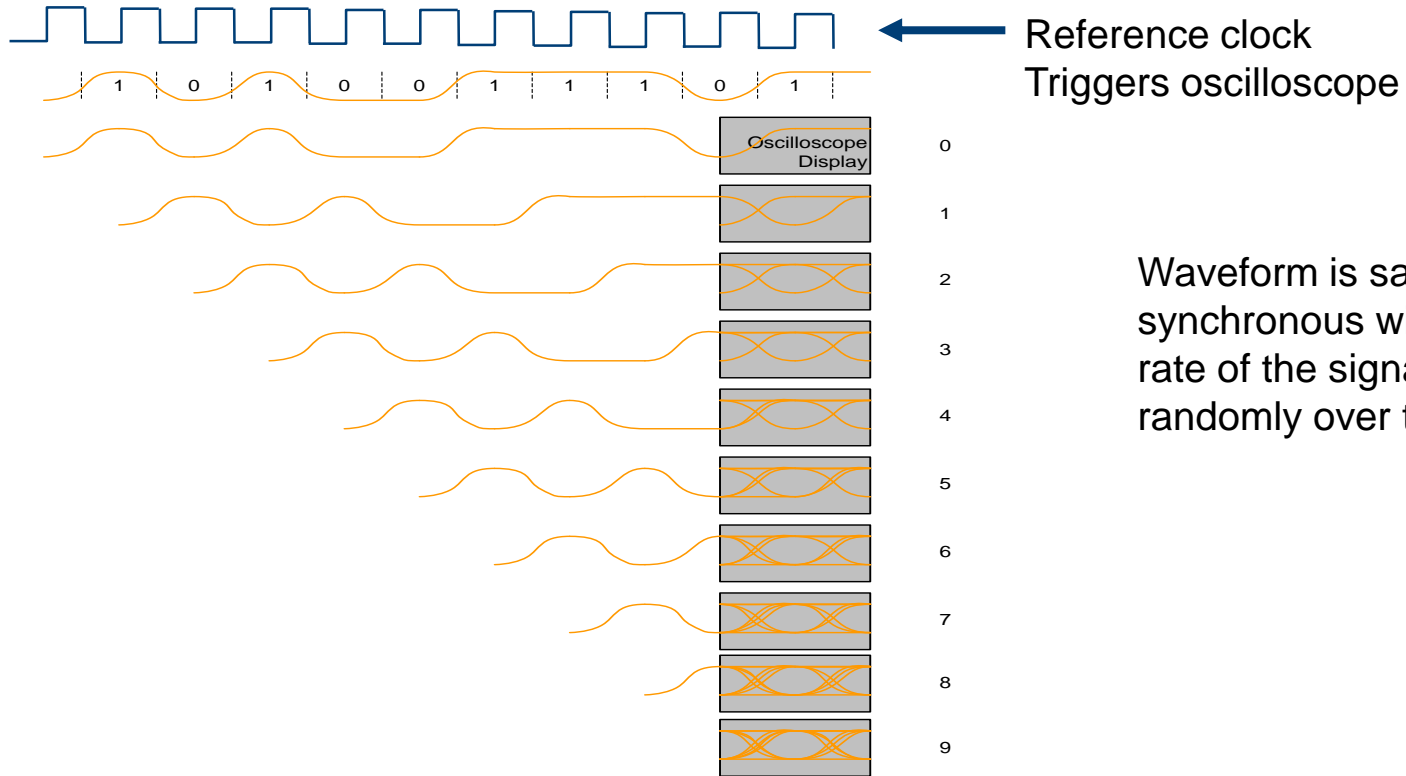
Automated Compliance Tests

- ▶ Verify compliance of the physical layer to interface standards and report results



EYE DIAGRAM BASICS

GENERATING EYE DIAGRAMS

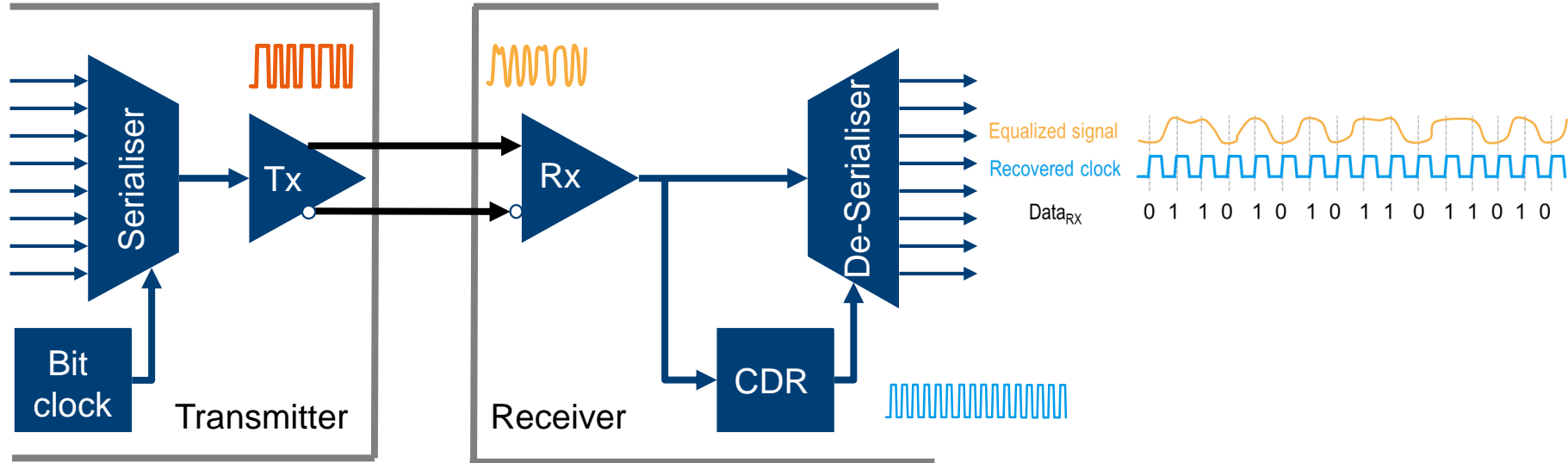


Waveform is sampled synchronous with the bit rate of the signal and randomly over time

REFERENCE CLOCK FOR EYE DIAGRAMS

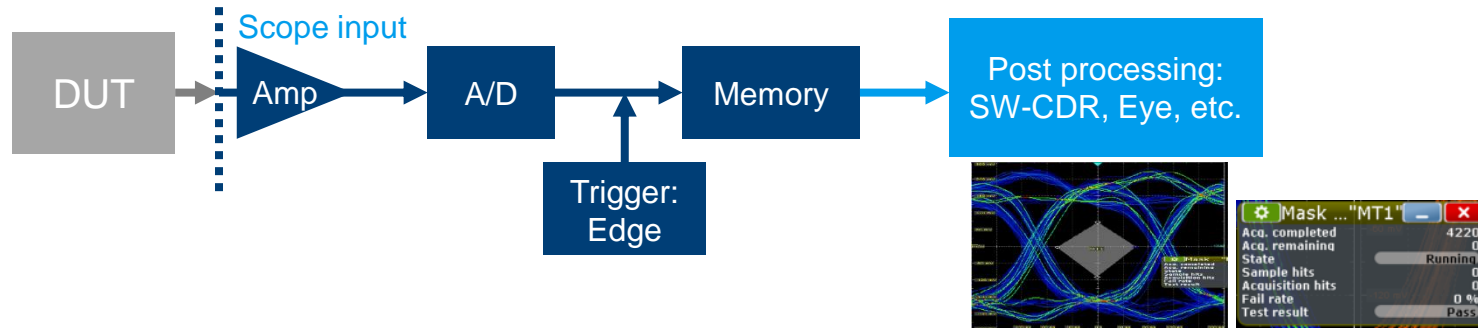
CLOCK-DATA-RECOVERY

- ▶ Timing Reference can be from a reference clock (parallel clock signal) or from the data signal itself (embedded clock signal)
- ▶ Clock data recovery is typically uses a Phase Locked Loop (PLL) or Delay Locked Loop (DLL)

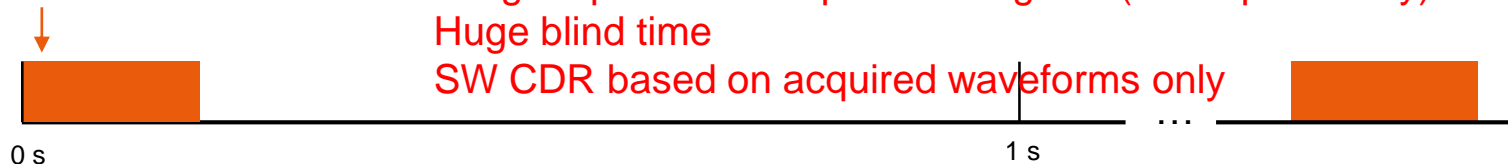


EYE DIAGRAM IN POST-PROCESSING

- ▶ Analysis based on a single acquisition with long Record length and SW-CDR in postprocessing
 - Acquired waveform is “folded” over into an eye based on software recovered clock
 - CDR – settling time (typ. >10us) and new synchronization for every new acquisition



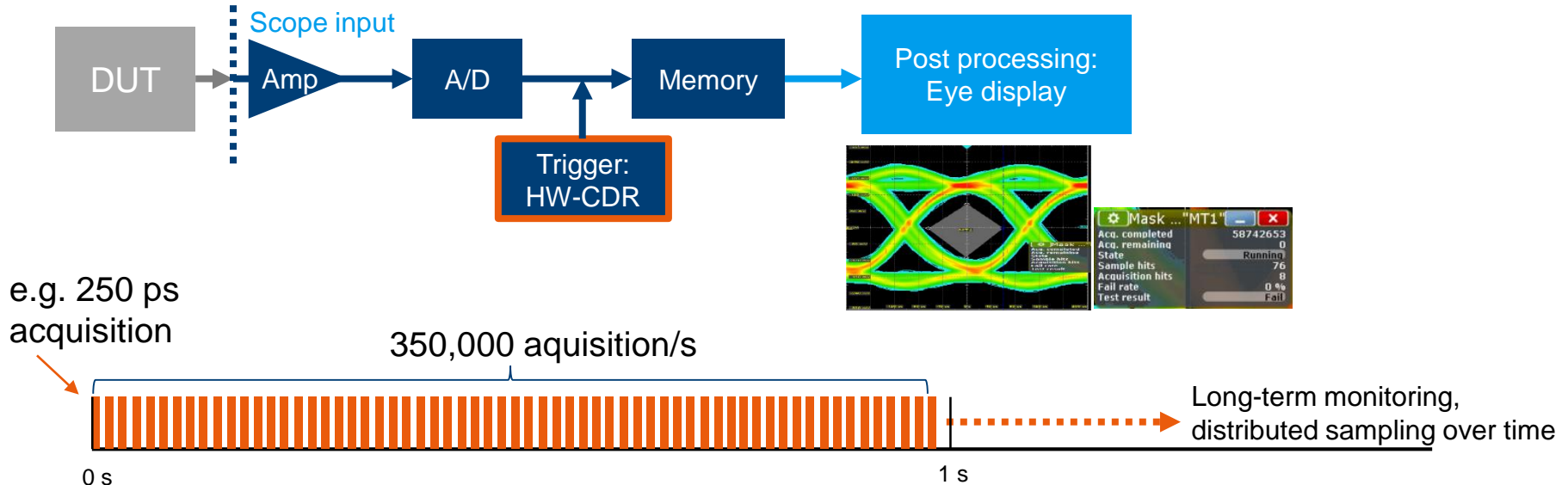
e.g. 100 us acquisition



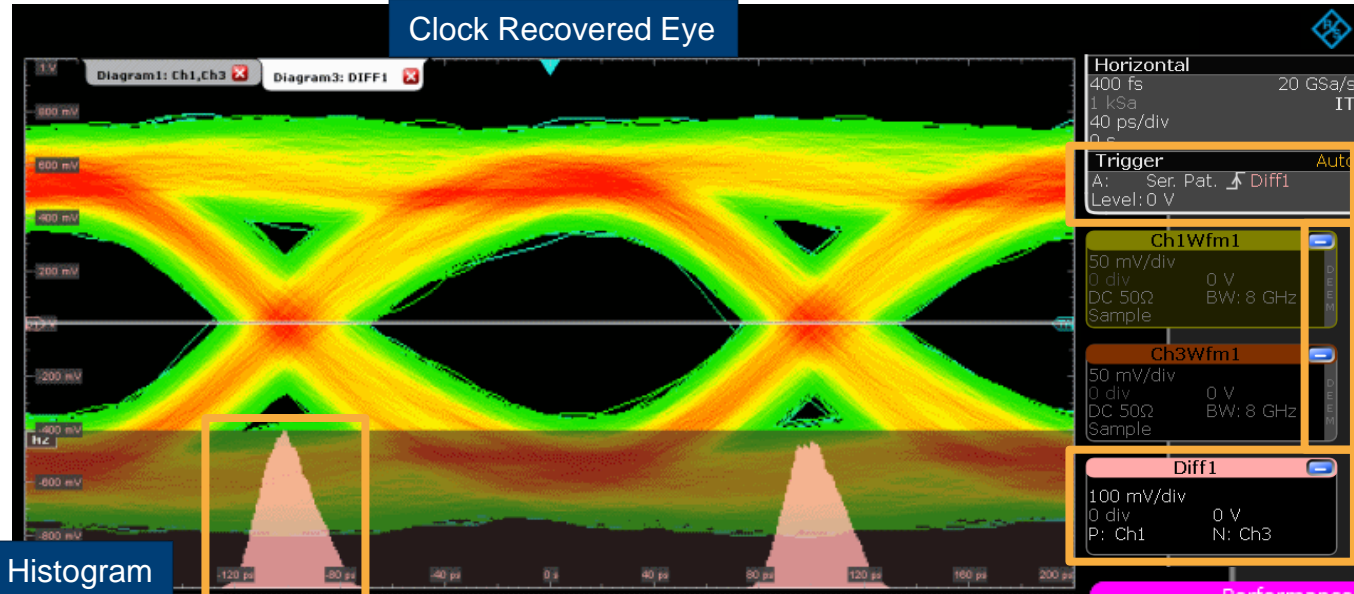
Long acquisition to capture enough UI (eats up memory)
Huge blind time
SW CDR based on acquired waveforms only

REALTIME EYE DIAGRAM

- ▶ Analysis based on a multiple acquisition, short Record Length and CDR in Hardware
 - Acquired bits are overlaid to an eye based on HW-CDR timing
 - CDR – looked once and runs continuously



MAKING IT FAST – REAL-TIME ANALYSIS



Clock Recovered Eye

Trigger On:
16 Gbps Serial Pattern
Differential Signal
De-Embedded Signal
Clock Data Recovered

Real-Time
De-Embedding

Real-Time
Differential Math

Histogram

Meas Group 1		Meas Group 2	
Eye height	695.65 mV	Waveform count	35699
Eye width	149.6 ps		
Noise (RMS)	73.203 mV		
Eye rise time	56.4 ps		
Eye fall time	57.6 ps		
Eye bit rate	5.01 GHz		
Jitter (RMS)	10.218 ps		

Millions of
Measurements

Performance

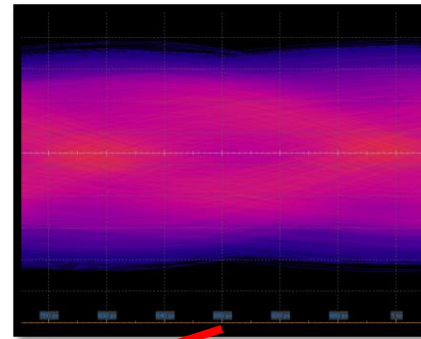
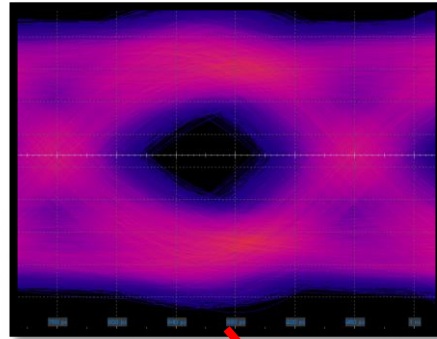
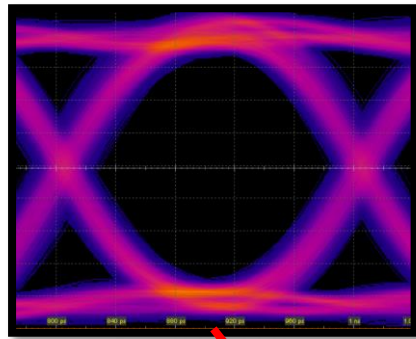
Acq/Fr	12090
Acq/s	398500
T/Fr	0.03

~400,000 UI/sec

Validation of digital design of next gen devices



CONCEPT OF DEEMBEDDING



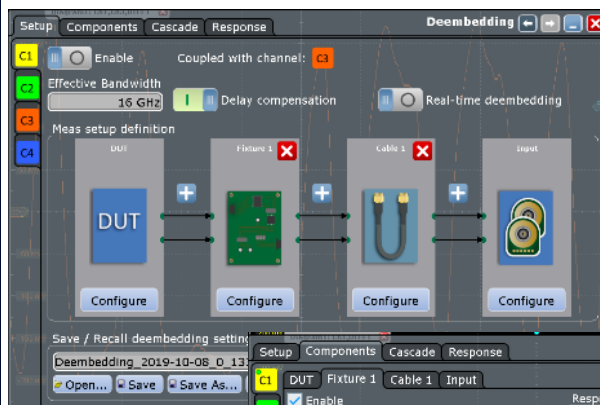
Transmitter

Receiver

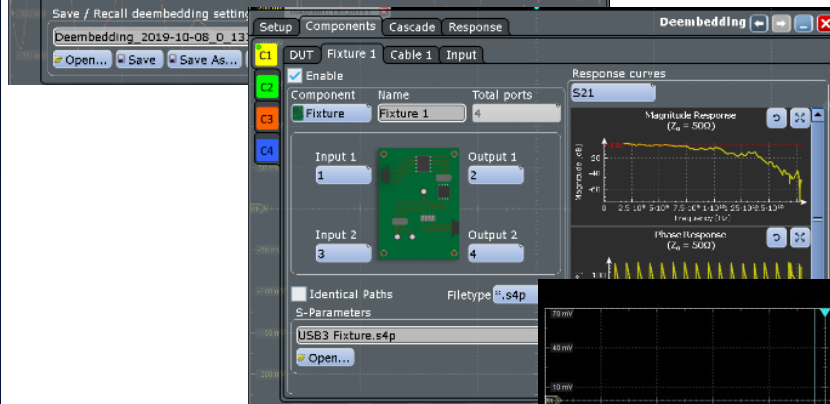


DEEMBEDDING MADE EASIER

- ▶ Option RTO/P-K121 + RTP-K122
 - SW and HW (Realtime)
- ▶ Applied during acquisition
- ▶ Trigger on de-embedded signal
- ▶ No update rate change
- ▶ Proven Cable / Probe
 - removes transmission loss effects
 - B7 pulse source

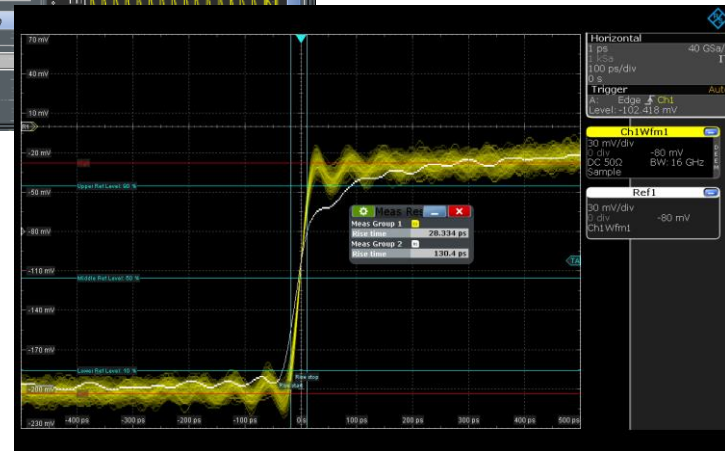


1. Define System Parameters



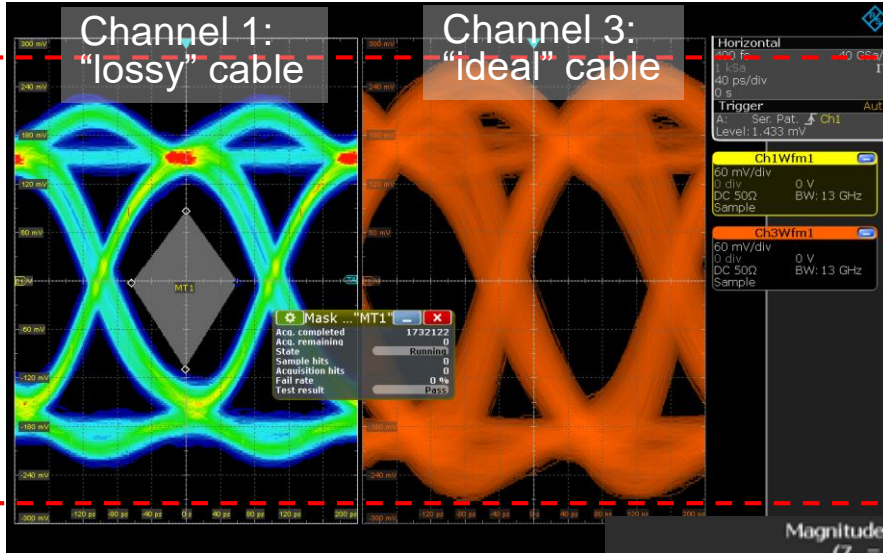
2. Import S-parameter

3. Observe deembedded response

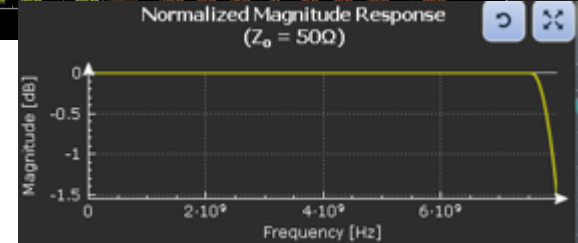
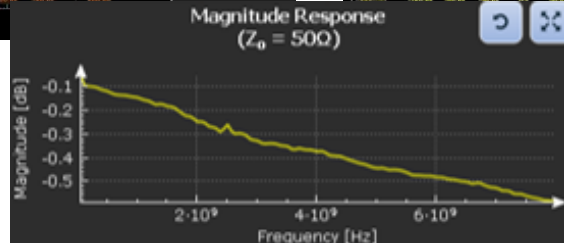
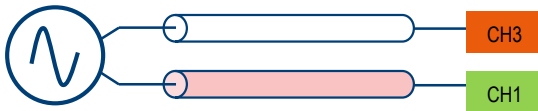
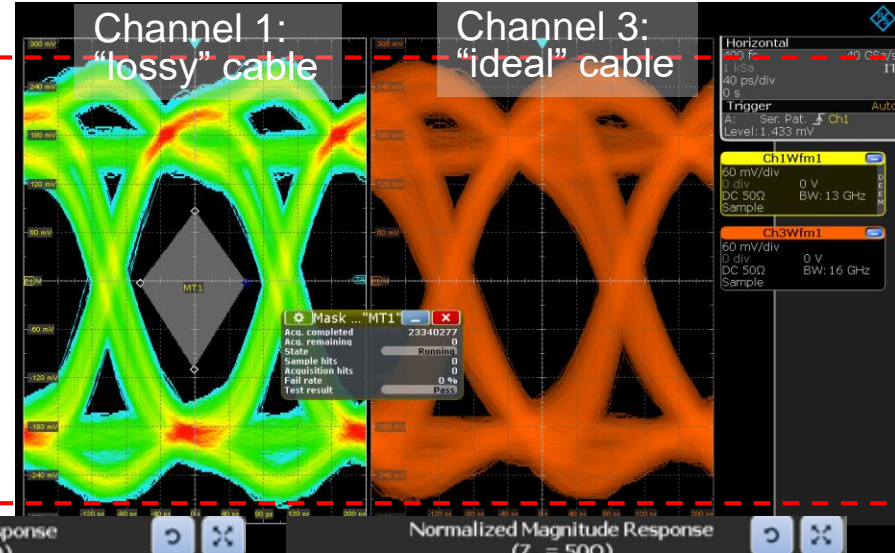


EXAMPLE – USB 3.2 GEN1 SIGNAL

De-embedding: OFF



De-embedding: ON

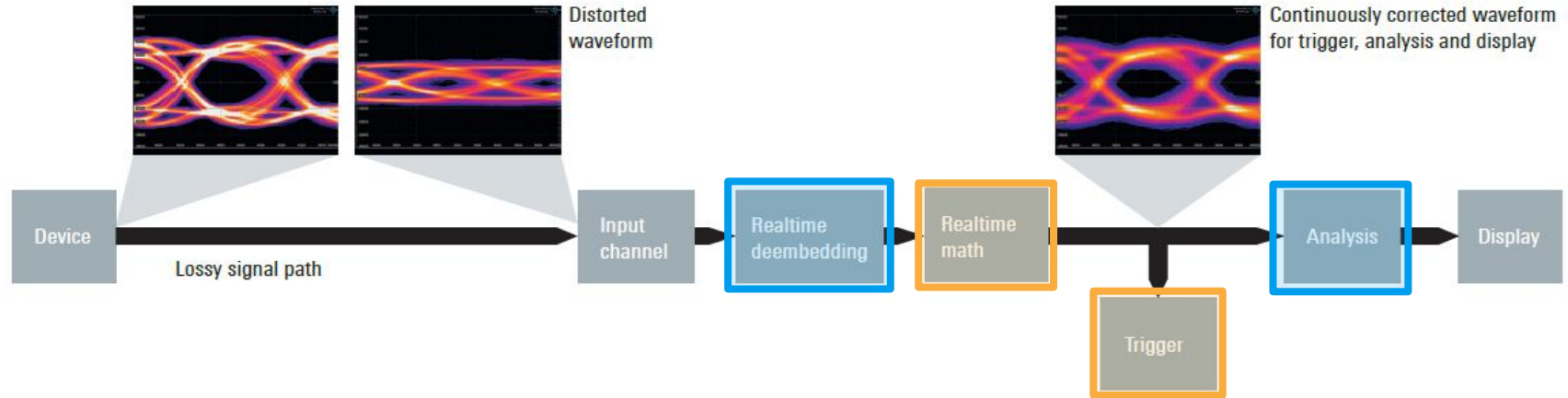


Rohde & Schwarz

Validation of digital design of next gen devices

REALTIME SIGNAL INTEGRITY UP TO 16 GHZ

Realtime Deembedding Architecture



Fast debugging

- ▶ 20 GSa/s: 750k wfm/s
- ▶ 40 GSa/s: 300k wfm/s

- ▶ Realtime transmission loss compensation

- ▶ RT-Math: V_{Diff} / V_{CM} Signals
- ▶ 16 Gbps Serial Trigger/CDR
- ▶ 25 ps glitch trigger

HW accelerated analysis:

- ▶ Mask Test
- ▶ Histogram

No time consuming post-processing

JITTER BASICS

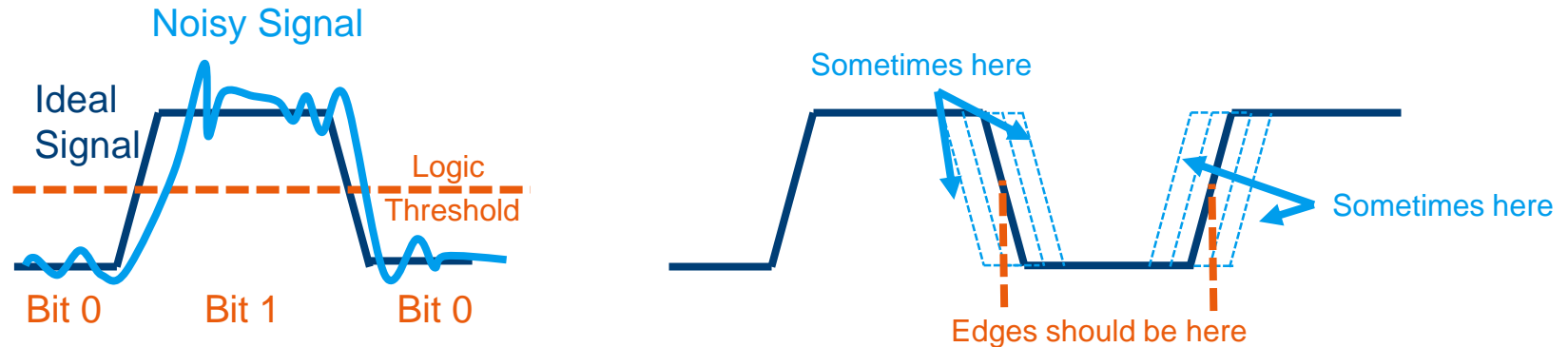
WHAT IS JITTER?

Timing Uncertainty

Frequency Domain
Phase Noise

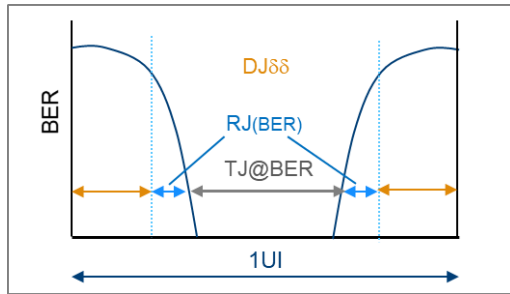
Time Domain
Jitter

Jitter is the short-term variations of a digital signal's transition edges from their ideal position



REASONS TO MEASURE JITTER

TJ Stability



Bathtub Plot

Measure Bit Error Ratio (BER) to 10^{-12}

"1 Bit Per every 1 Trillion Bits"

Oscilloscopes estimates it

Standards Requirement

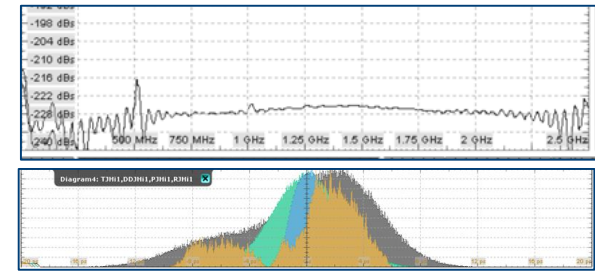
Table 4-4: Total System Jitter Budget for 5.0 GT/s Signaling

Jitter Contribution	Max RMS Rj (ps)	Max Dj (ps)	Tj at BER 10^{-12} (ps)
Tx	1.4	30	50
Ref Clock	3.1	0	43.6
Media	0	58	58
Rx	1.4	60	80
Linear Total Tj:			231.6
Root Sum Square (RSS) Total Tj:			200

USB spec require RJ, DJ and TJ @ 10^{-12}

Standards require separation and provide limits

Debugging



Find root cause sources

What-if you fix it? Analysis

JITTER COMPONENTS

Total Jitter is composed out of several jitter contributions:

- Random Jitter: “unbounded”
- Deterministic Jitter: usually “bounded”

Total Jitter (TJ)



EVOLUTION OF SEPARATION ALGORITHMS

A New Method for Jitter Decomposition Through Its Distribution Tail Fitting
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Abstract
 media, reflections, cross-talk, electromagnetic interference (EMI), synchronization uncertainties, and pattern dependency, for DQ and thermal noise, shot noise, flick noise, random modulation, non-stochastic interference, for RJ. In the real world applications, what is measured, in general, is the total jitter, namely both DJ and RJ are mixed together. The

We present a new time-domain jitter separation method. Such a method automatically searches and fits the tail parts of the jitter histogram with multiple jitter models and

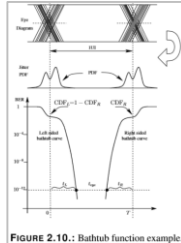
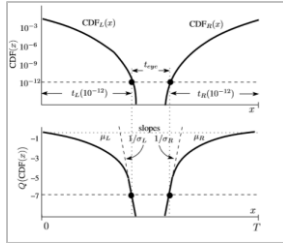


FIGURE 2.10.: Bathtub function example.

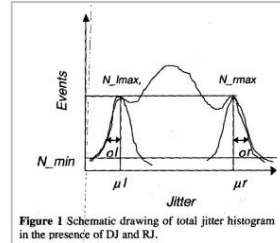
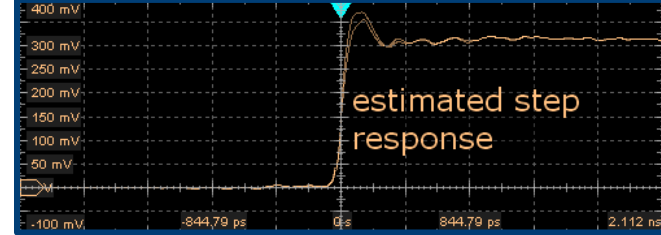


Figure 1 Schematic drawing of total jitter histogram in the presence of DJ and RJ.



Jitter Separation
 "Tail"-fitting &
 Dual-Dirac-Model

Extension with
 Transformation into Q-
 Space

R&S's modern approach:
 Signal-Model-based

2000

2008

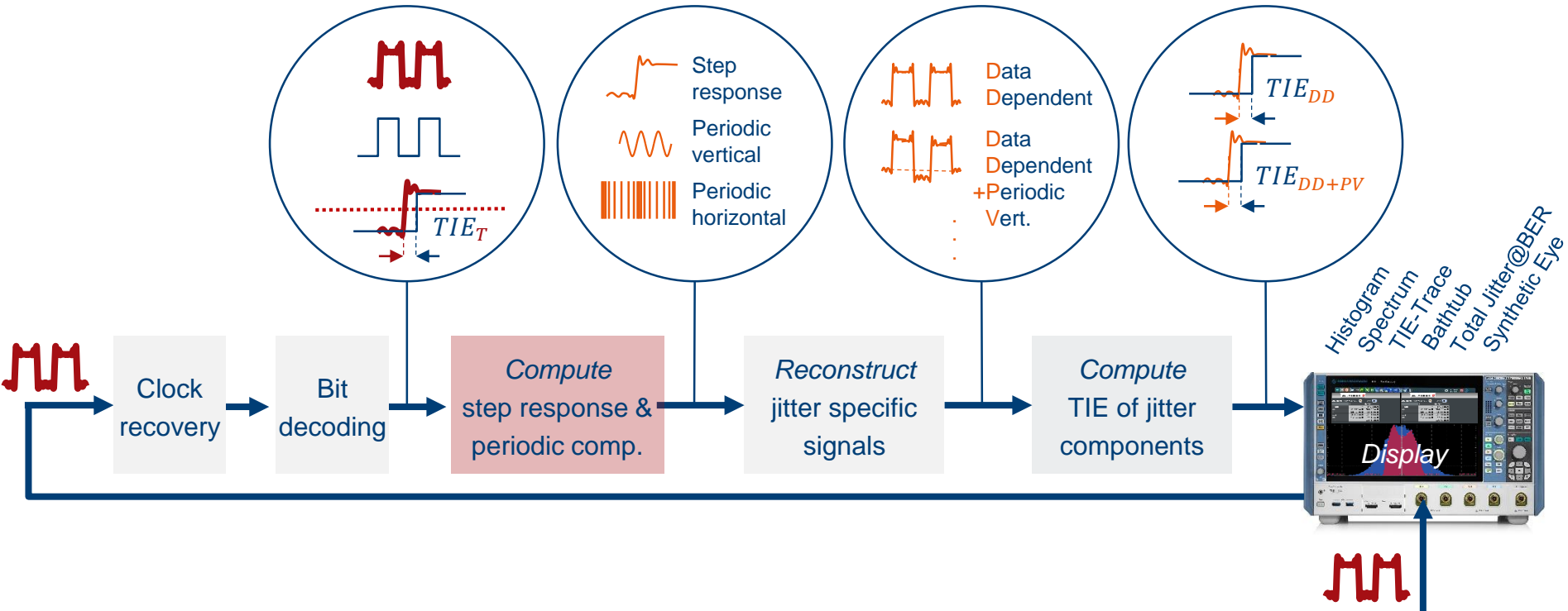
2020

Extensions DDJ/ISI/DDC and
 spectrum view for PJ, etc.

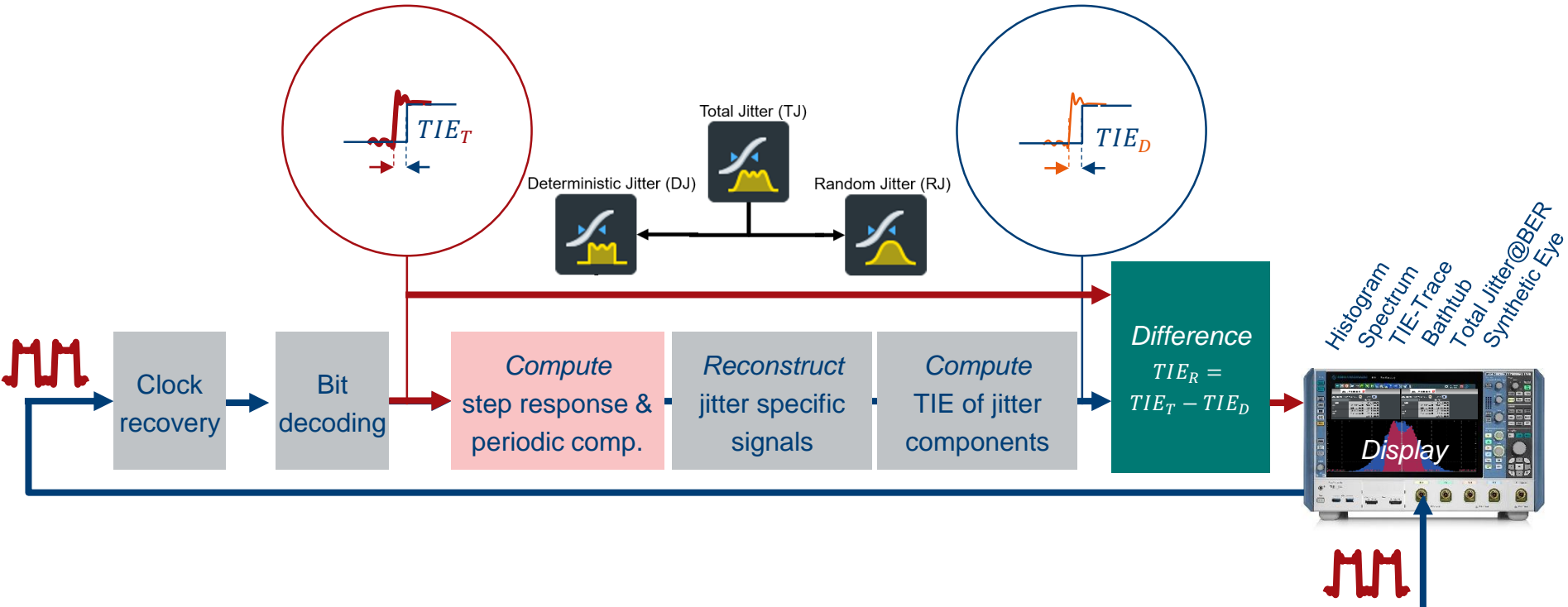
Extension with
 Noise Separation



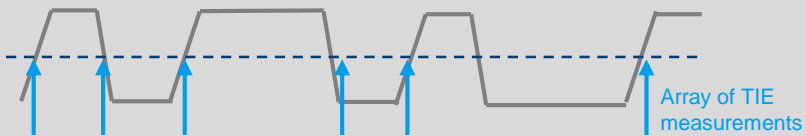
NOVELL R&S APPROACH DETERMINISTIC COMPONENT



NOVELL R&S APPROACH RANDOM COMPONENT

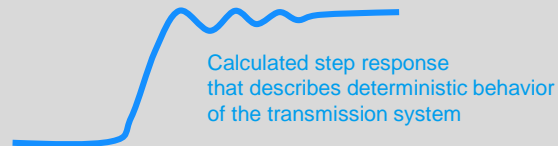


Legacy TIE-based approach



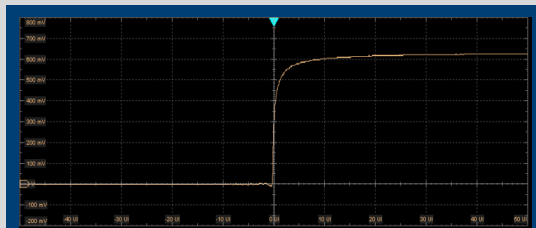
- ▶ Reduce Signal information to a set of TIE measurements at a voltage threshold

▶ R&S's Signal Model-based approach

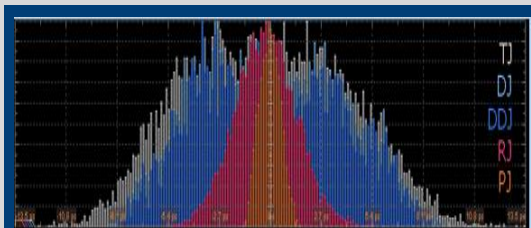


- ▶ Parametric signal model with all signal information for most accurate and reliable jitter decomposition

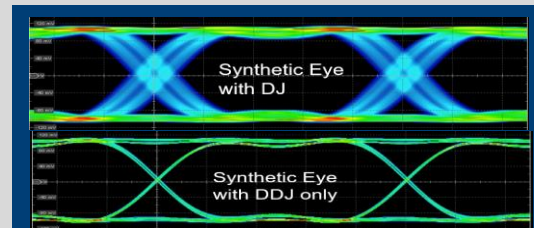
Use more result data for faster debugging



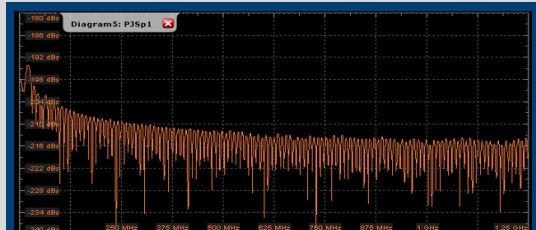
Understand channel characteristic



View individual jitter components



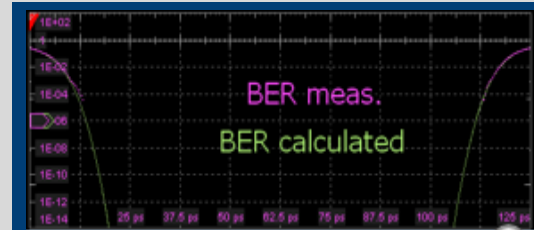
Select what jitter component to include



Detect root cause of PJ in spectrum

Periodic components 1			
Frequency	Value	Direction	
1	19 MHz	50.481 ps	Horizontal
2	4.5032 MHz	28.695 ps	Horizontal
3	57.001 MHz	13.543 ps	Horizontal
4	684.63 kHz	4.8239 ps	Horizontal
5	95.001 MHz	4.8077 ps	Horizontal
6	19.685 MHz	1.977 mV	Vertical
7	39.369 MHz	1.4551 mV	Vertical
8	59.055 MHz	747.16 μ V	Vertical
9	6.2992 GHz	54.494 μ V	Vertical
10	6.2598 GHz	32.261 μ V	Vertical

Detect root cause of PJ in table report



Calculate TJ for all or selected components

AUTOMATED COMPLIANCE SOFTWARE

TESTING BASED ON COMPLIANCE REQUIREMENT



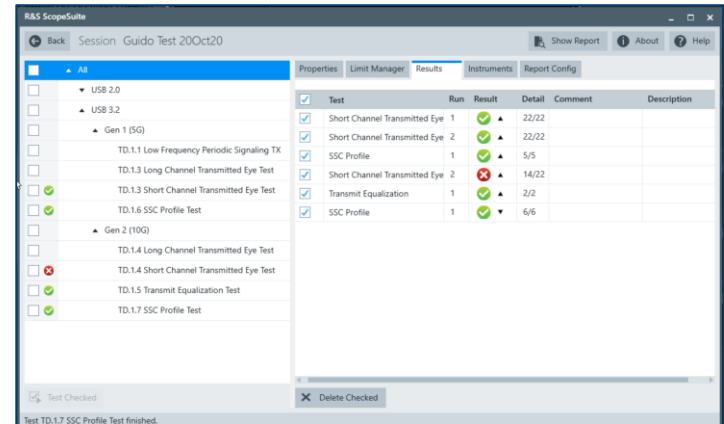
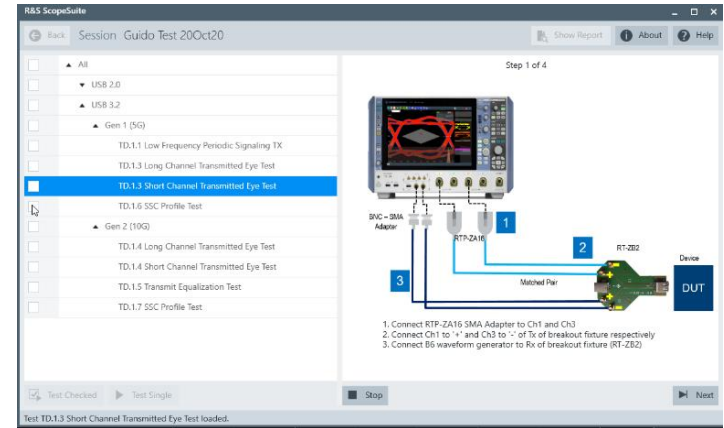
Electrical specifications in each standard committees covers all the measurement requirement but it will be difficult to manually execute all the requirements

- ▶ Specified measurement algorithm and setup
- ▶ Additional signal processing as per required by standards (deembedding & CDR)
- ▶ Guidance to depict the set necessary test modes and fixtures setup

Most standard bodies still required DUT to be tested by official test house or allow submission of compliance report.

SCOPESUITE COMPLIANCE

- ▶ Automated Compliance Test following standards
- ▶ R&S ScopesSuite Wizard
 - Guided test execution
 - Flexible test operation (incl. re-tests)
 - Limit manager
 - Detailed test reports



POWER INTEGRITY

What are the right tools and analyzing functions for appropriate characterizing & debugging?

POWER INTEGRITY CHALLENGES

- ▶ Increasing number of power rails
- ▶ Lower margins due to lower supply voltages
- ▶ Interferences due to dense designs of mixed technologies

An optimal solution for characterizing and debugging DC power rails demands suitable probes & oscilloscopes.



POWER INTEGRITY

Requires Dedicated Tools for Verification & Debugging

The Right Scope

- ▶ Fast update rate
- ▶ Min. vertical scale: 1..2 mV/div in HW at full bandwidth
- ▶ Low noise
- ▶ Support of specialized probes also on high-performance class instruments

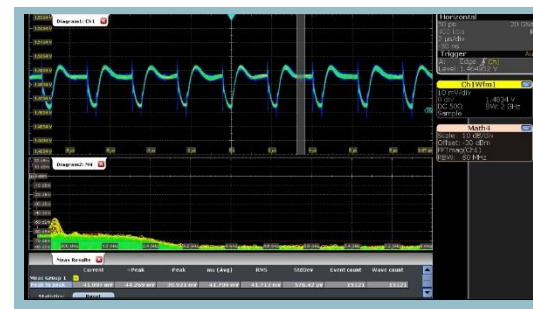
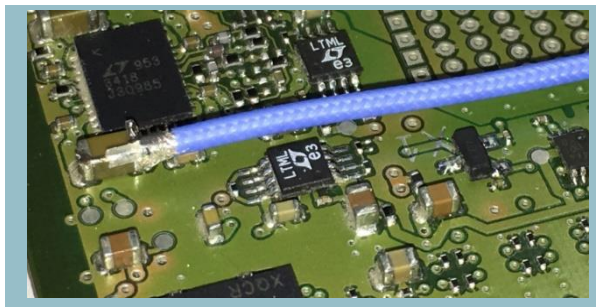
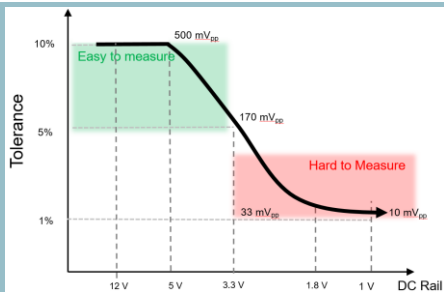
Specialized Probes

- ▶ Power Integrity Probe
 - Bandwidth >2 GHz
 - Low noise with 1:1 attenuation
 - Extended offset range
 - Connectivity
- ▶ Current probes, etc.

Dedicated Analysis Functions

Typical measurements

- ▶ Ripple, Load step response
- ▶ Power-up/down, Sequencing
- ▶ Drift over temperature and input voltage
- ▶ EMI debugging / harmonic analysis

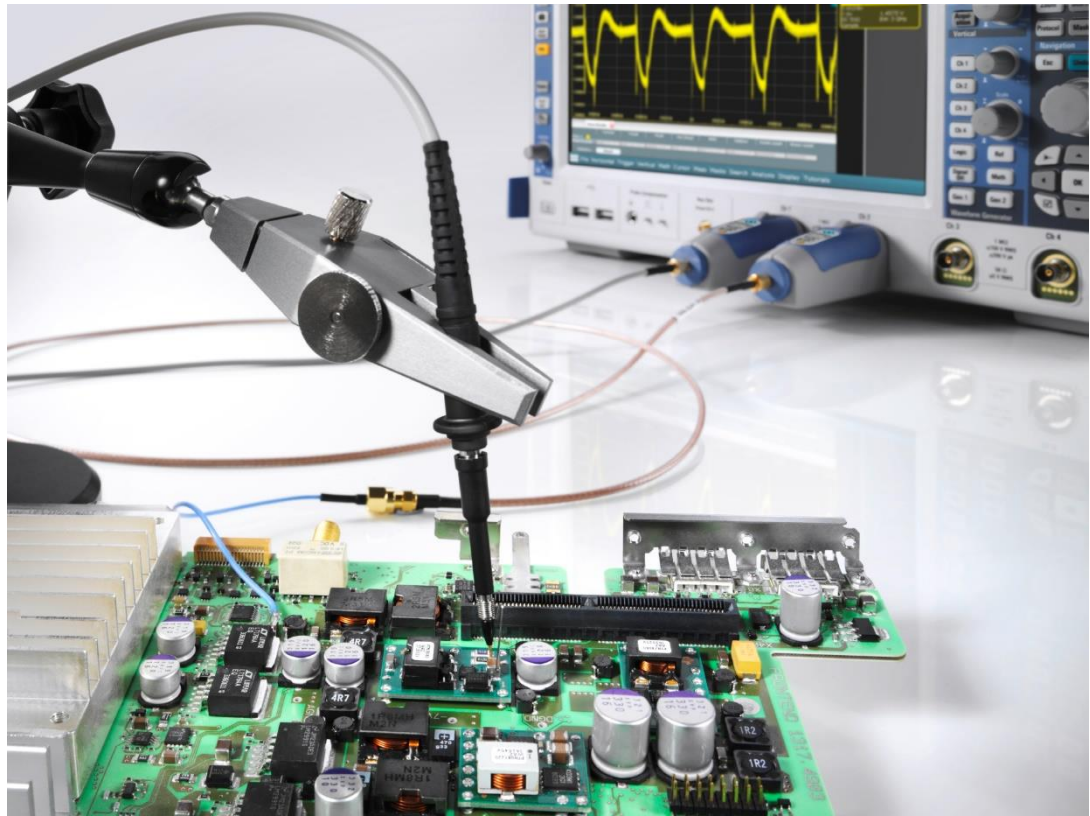


R&S POWER INTEGRITY SOLUTION

- ▶ Low Noise
- ▶ Fast FFT
- ▶ Fast Update Rate

- ▶ Low-Price Alternatives
-RTM / RTA Oscilloscopes

- ▶ Superior Power Rail Probes

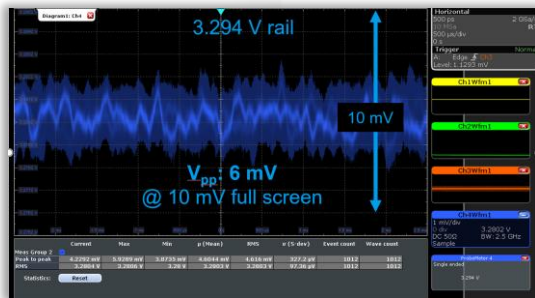


Providing Unique Power Integrity Analysis Functions

DEDICATED POWER RAIL PROBING SOLUTION

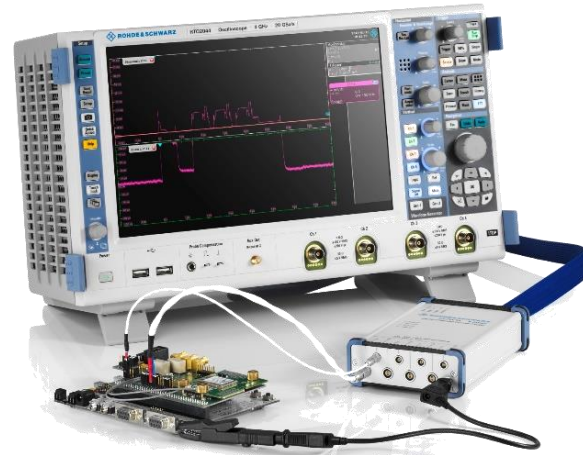
RT-ZPR20/40 Power Rail Probes

- ▶ Active, single-ended probe
- ▶ Very low noise with 1:1 attenuation
- ▶ Best in class offset compensation capability



RT-ZVC Probe for Power Consumption

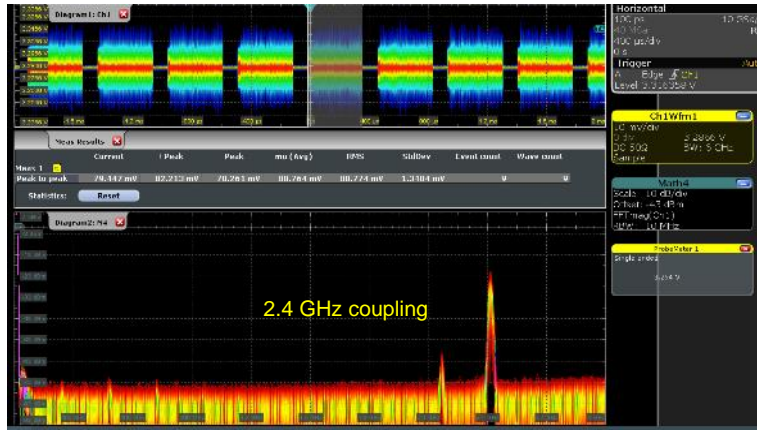
- ▶ 18-bit vertical resolutions for each channels
- ▶ 0.1% measurement accuracy
- ▶ <2 nA AC RMS noise



UNIQUE ANALYSIS FUNCTIONS IN ONE INSTRUMENT

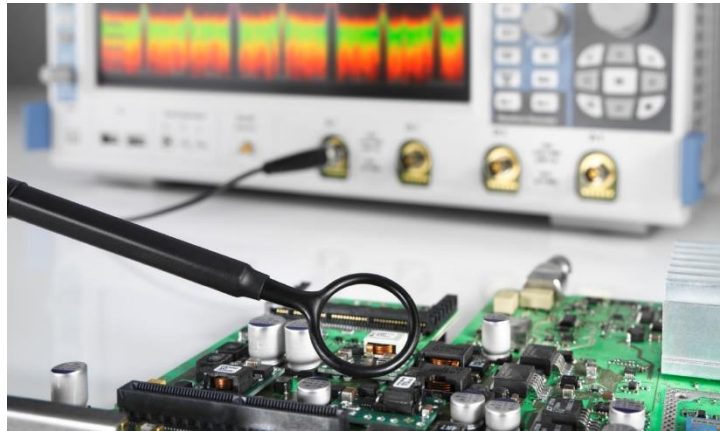
Superior FFT Performance

- ▶ Fast and responsive FFT to detect interferer
- ▶ Multi-channel Math FFT for comparison
- ▶ Time and frequency domain correlation



EMI Debugging Capability

- ▶ Log scale display to match Test Receiver presentation
- ▶ Limit line capability with zone trigger to detect violation
- ▶ Math on FFT for further EMI testing & analysis



DEDICATED INSTRUMENT FOR SPECIALIZED TESTING

Using the best tool for specific measurements.

DIGITAL DESIGN TEST



Network Analyzers
e.g. ZNA, ZNB, ZNL



Scopes
e.g. RTP, RTO, RTE



**Phase Noise Testers,
Spectrum Analyzers**
e.g. FSWP, FSW



Power Supplies
e.g. HMP, NGL



Signal Generators
e.g. SMA100B, SMW

Optical Interface
ADC / DAC Verification

Clock Tree
Verification

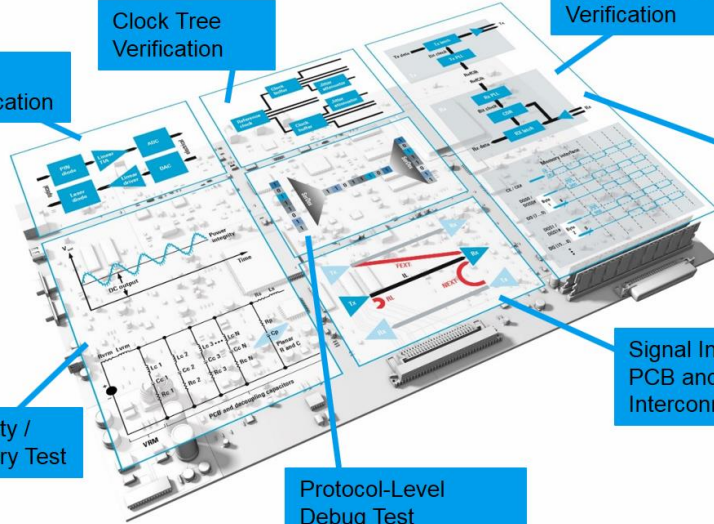
SERDES PLL and ADC / DAC
Verification

Signal Integrity:
Interface Test

Power Integrity /
Power Delivery Test

Signal Integrity:
PCB and
Interconnect Test

Protocol-Level
Debug Test



R&S RTP HIGH-PERFORMANCE OSCILLOSCOPE

- ▶ 4-16 GHz bandwidth
- ▶ Dedicated hardware for real-time Signal-Integrity
- ▶ Most compact & silent for everyday use in the lab



Providing Unique Signal Integrity Analysis Functions

SUMMARY

- ▶ Digital design is the backbone for the next generation devices and infrastructures
- ▶ Technology advances push complexities into design as well as measurement requirements
- ▶ Signal integrity ensure best performance for design interconnects which need a versatile tool to help characterizing and debugging
- ▶ Power integrity is often forgotten but plays an important role that affects the design performance

Next generation build on the fundamental performance of the devices and infrastructure, making sure these designs works will be crucial for your 5G Testing Journey!





4th May

Validation of digital design of next gen devices



11th May

Challenges to 5G mmWave component characterization



25th May

Simplifying 5G mobile device testing



1st June

ONE tool for automated device testing



8th June

Making 5G lab testing more realistic with R&S®CM360°



15th June

Production test strategies and smart solutions

5G DEVICE TESTING JOURNEY

Webinar Series

5G Device testing journey

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